

# SPECIAL PURPOSE HI-TEMP ADHESIVES

## For Electronic and Metallurgical Applications

### 2500°F - RESBOND 905

#### Low Expansion Adhesive

**Resbond 905 Quartz** (fused silica) Adhesive was specially formulated for bonding low expansion and thermal shock resistant ceramics.

The thermal expansion of Resbond 905 closely matches the extremely low expansion of Quartz, Fused Silica, Corderite and Lithium-Alumina Ceramics.

These shock resistant ceramics can now be successfully bonded and used to 2500°F.

Replaces standard ceramic adhesives that may crack and weaken on thermal cycling.

Just apply and let dry. Resbond 905 is resistant to most chemicals and solvents.

#### Users Report:

- Resbond 905 bonds and electrically insulates quartz light bulbs and fixtures.
- Resbond 905 bonds quartz to stainless steel to aid in processes designed to cool hot silicone.
- Resbond 905 successfully bonds colored glass panels to a halogen lamp, creating a crack resistant decorative lamp.



**905 Bonds a High Performance Quartz Lamp**



**906 Bonds a Stainless Assembly**

### 3000°F - RESBOND 906

#### High Expansion Adhesive

**Resbond 906 Magnesia Based Adhesive** was formulated for bonding high expansion materials for use to 3000°F.

Bonds to steel, stainless, aluminum, brass, copper, silver, nickel and other high expansion materials.

Resbond 906 will cure at room temperature to form a highly thermally conductive bond.

Strength and moisture resistance will be improved by a post cure at 600°F - 700°F.

Resbond 906 has excellent resistance to oxidizing and reducing atmospheres, most chemicals and solvents.

It is resistant to flame impingement and most liquid metals.

#### Users Report:

- 906 forms a thermally conductive and electrically insulating bond for Hi - Watt Density Heater.
- Coated Hi - Watt density heating coils before insertion into stainless steel tubes. Did not crack when exposed to vibration and high temperatures.
- Bonded re-crystallized alumina tubes to PTFE insulated cable for use at 700°F.

**Applications include:** bonding high expansion materials, forms highly thermally conductive bonds, potting and encapsulating heating assemblies. etc.

RESBOND	905	906
Major Constituent	QUARTZ	MAGNESIA
Temp Limit °F	2500	3000
Thermal Expansion (x 10 <sup>-6</sup> /°F)	0.3	7
Thermal Conductivity (BTU in / Hr °F Ft <sup>2</sup> )	10	40
Compressive Strength (psi)	3200	3000
Flex. Strength (psi)	2100	1500
Dielectric Strength (volts/mil)	200	250
Volume Resistivity (ohm - cm)	10 <sup>11</sup>	10 <sup>9</sup>
Components	2	2
Mix Ratio	100/60	100/42
Color	White	White
Consistency	Paste	Paste

#### Cat No.

#### Size

Resbond 905-1 . . . . . Pint

Resbond 905-2 . . . . . Quart

Resbond 905T-1 . . . . . Thinner - Pint

Resbond 906-1 . . . . . Pint

Resbond 906-2 . . . . . Quart

Resbond 906T-1 . . . . . Thinner-Pint

**Production Pricing is Available Upon Request**

**Zur Beachtung:**

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**Änderungen vorbehalten / Stand: 07/2009**